

# Stitch Aware Detailed Placement for Multiple E-Beam Lithography

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# Outline



- Introduction
- Previous Work
- Problem Formulation
- Stitch Aware Detailed Placement
- Experimental Results
- Conclusion

# Introduction



## Technology Scaling

		Uni-directional parallel line/space patterning techniques																							
		CD	40	38	36	34	32	30	28	26	24	22	20	18	16	14	12	10	8	6					
Exposure tool	Pitch	80	76	72	68	64	60	56	52	48	44	40	36	32	28	24	20	16	12						
Immersion	→	[Production]																							
Immersion	→	[Production]					19	[Opportunity]			20	[Extendability]													
Immersion	→	[Production]											2	[Extendability]											
Immersion	→	[Production]											5	1	[Extendability]		[Opportunity]								
EUV	→	[Opportunity]											[Extendability]		18	[Opportunity]									
EUV	→	[Opportunity]											4	[Extendability]		6	[Opportunity]								
Immersion	→	[Opportunity]											[Extendability]		3	12	[Opportunity]								
ArF, EUV, E-beam	→	[Opportunity]											[Extendability]		[Opportunity]		11	[Opportunity]							
Nanoimprint	→	[Opportunity]											[Extendability]		13	[Extendability]		14	[Opportunity]						
High NA EUV	→	[Opportunity]											[Extendability]		[Extendability]		17	[Opportunity]							
E-beam	→	7	[Opportunity]			[Opportunity]			8	[Extendability]		[Extendability]		15	[Extendability]		16	[Opportunity]							
E-beam	→	[Opportunity]											[Extendability]		9	10	[Extendability]		[Opportunity]						

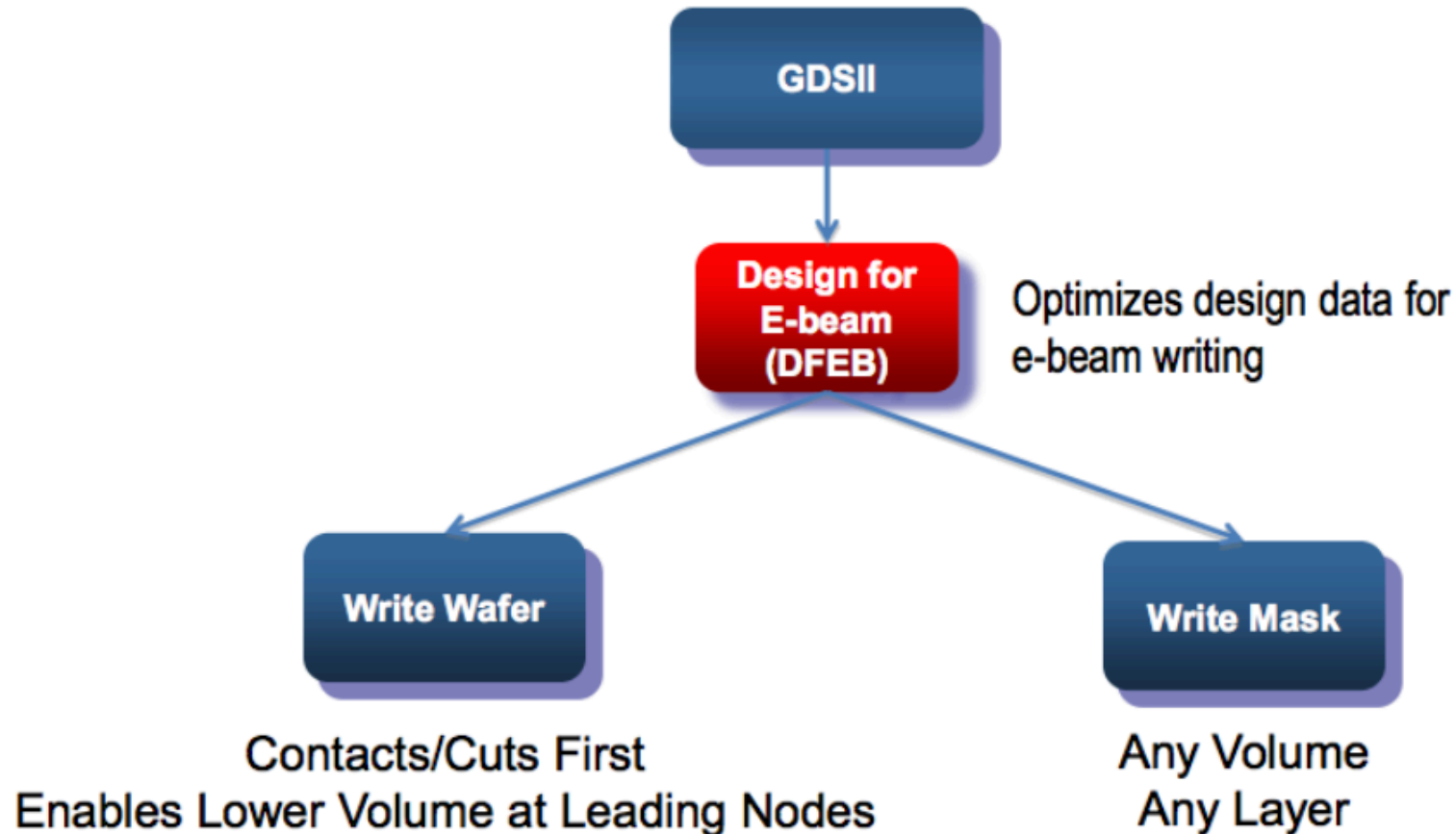
[Courtesy ITRS]

Consenses that technique has been used in production  
 Published demonstrations from potential deployable equipment show opportunity for production  
 Simulations, surface images, or research grade demonstration suggest potential for extendability

# E-Beam Lithography



- Direct-write or mask?

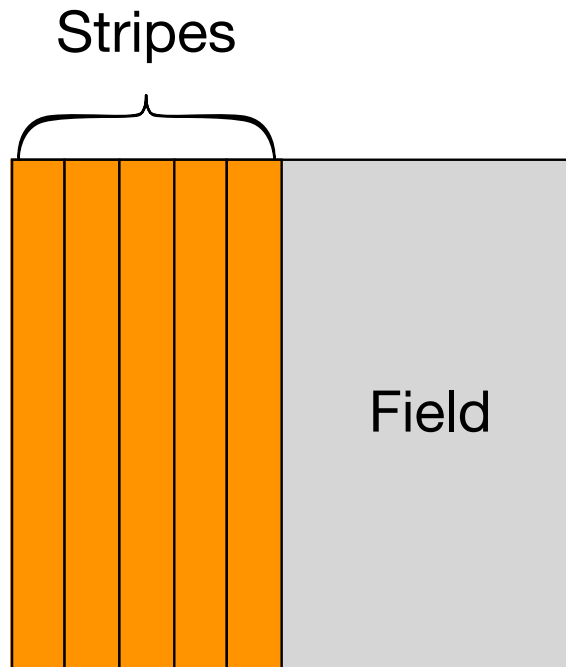


[Courtesy E-beam Initiative]

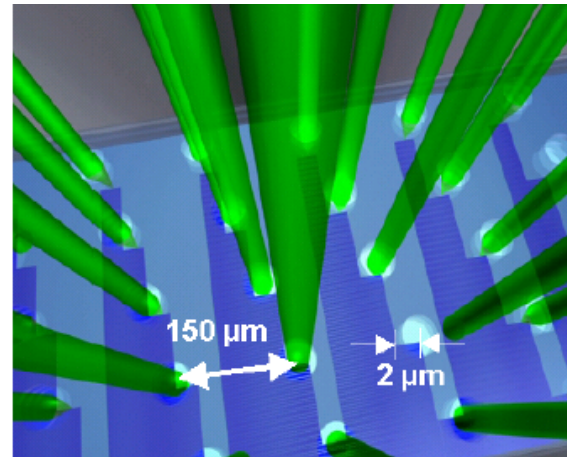
# Multiple E-Beam Lithography



- Massively-Parallel e-beam writing
  - Each stripe has width of 50~200 microns
  - Stitching region has a width around 15nm [Berg+, SPIE'11]
  - Field stitching



[Fang+, DAC'13]

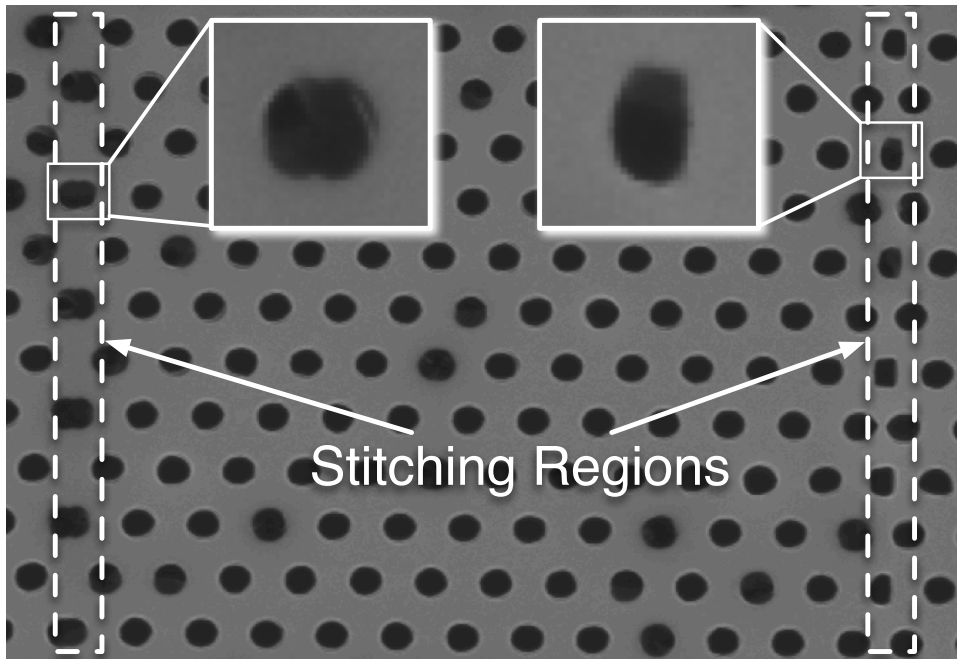


MAPPER Lithography System

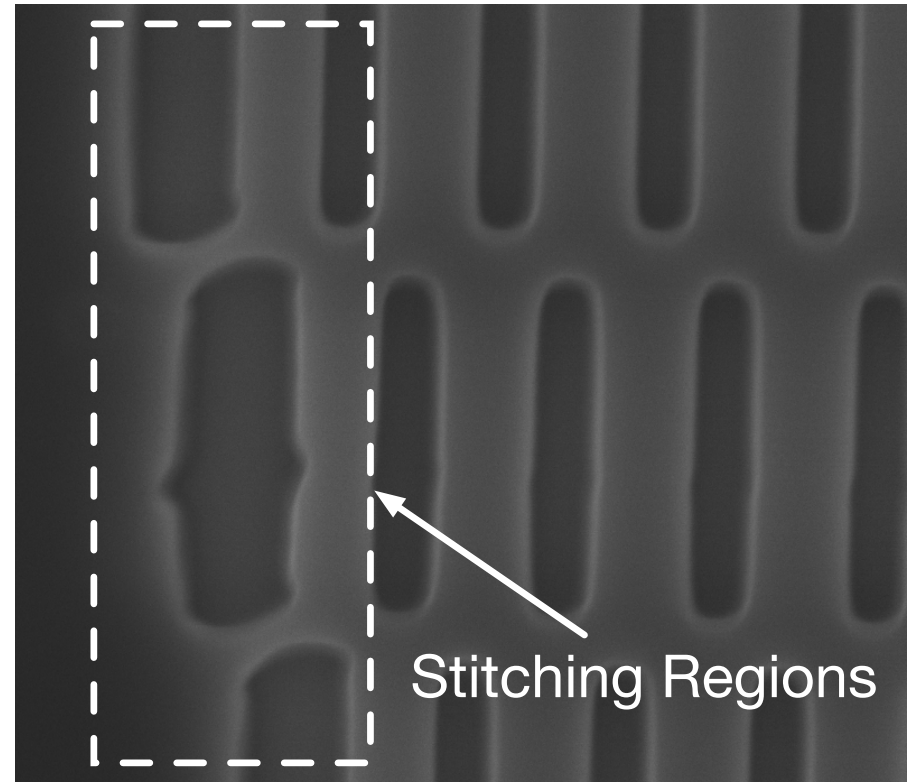
# Field Stitching



- SEM figures showing stitches at boundaries of beam stripes



Holes



Lines

# Previous Work

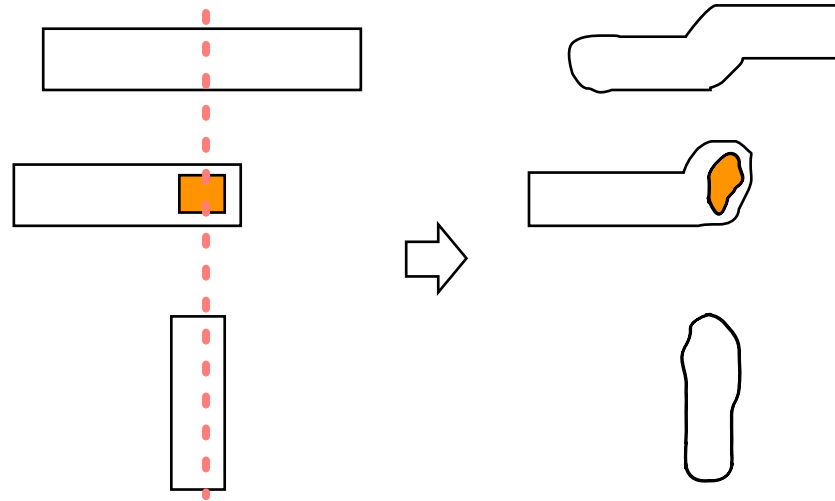


- Stitch aware routing for MEBL
  - [Fang+, DAC'13], [Liu+, TCAD'15]
- TPL aware placement
  - [Yu+, TCAD'15], [Kuang+, TVLSI'15], [Chien+, TCAD'15]
  - [Tian+, ICCAD'14], [Lin+, ISPD'15]
  - TPL applies **different** constraint to placement from MEBL
- No placement algorithm addressing MEBL stitch constraint yet

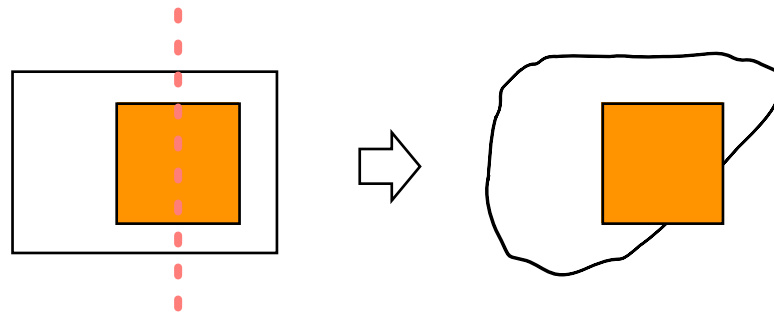
# Stitch Errors



- Defects on vias and vertical wires



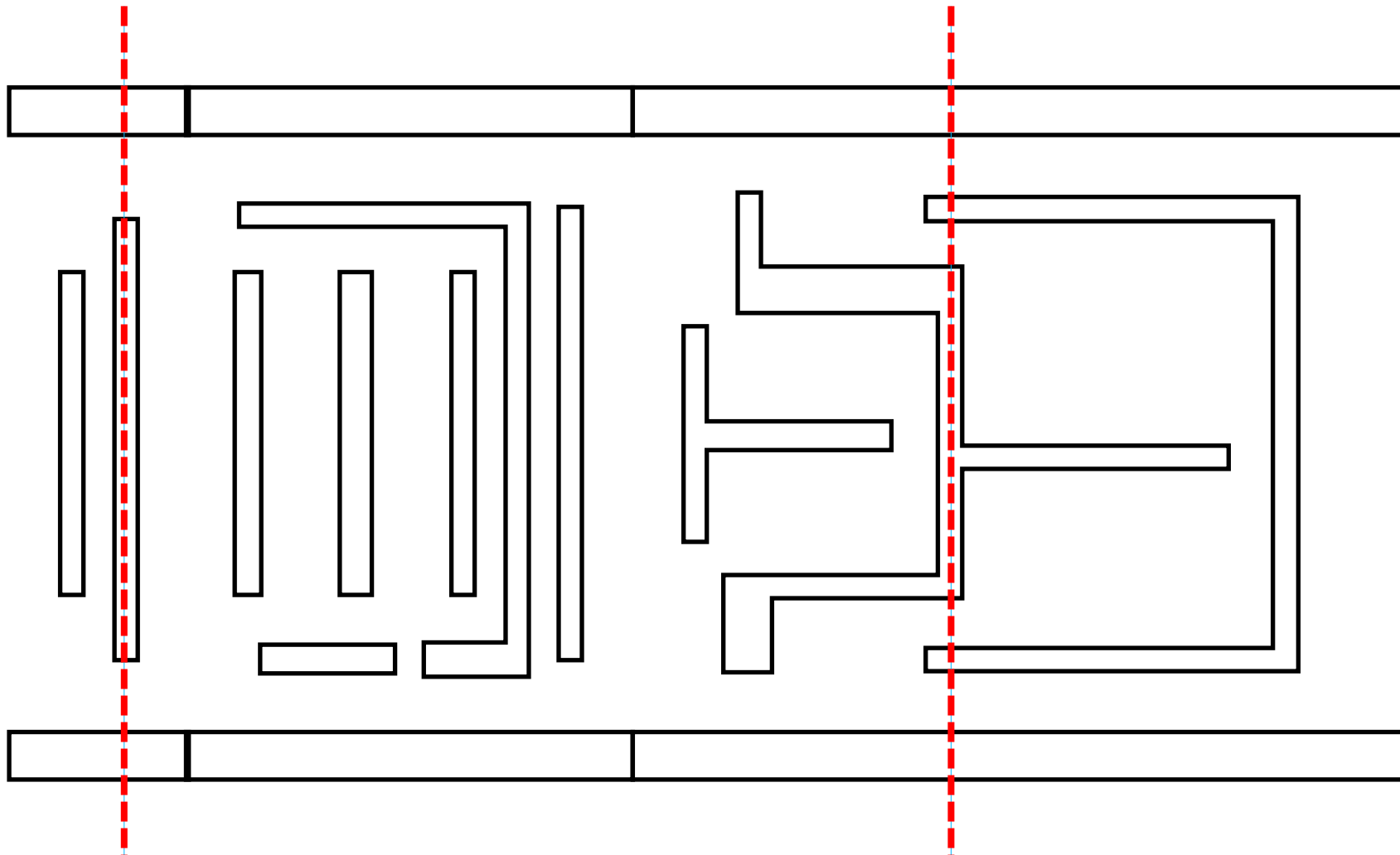
- Defects on short polygons



[Fang+, [DAC2013](#)]



# Stitch Errors within Standard Cell

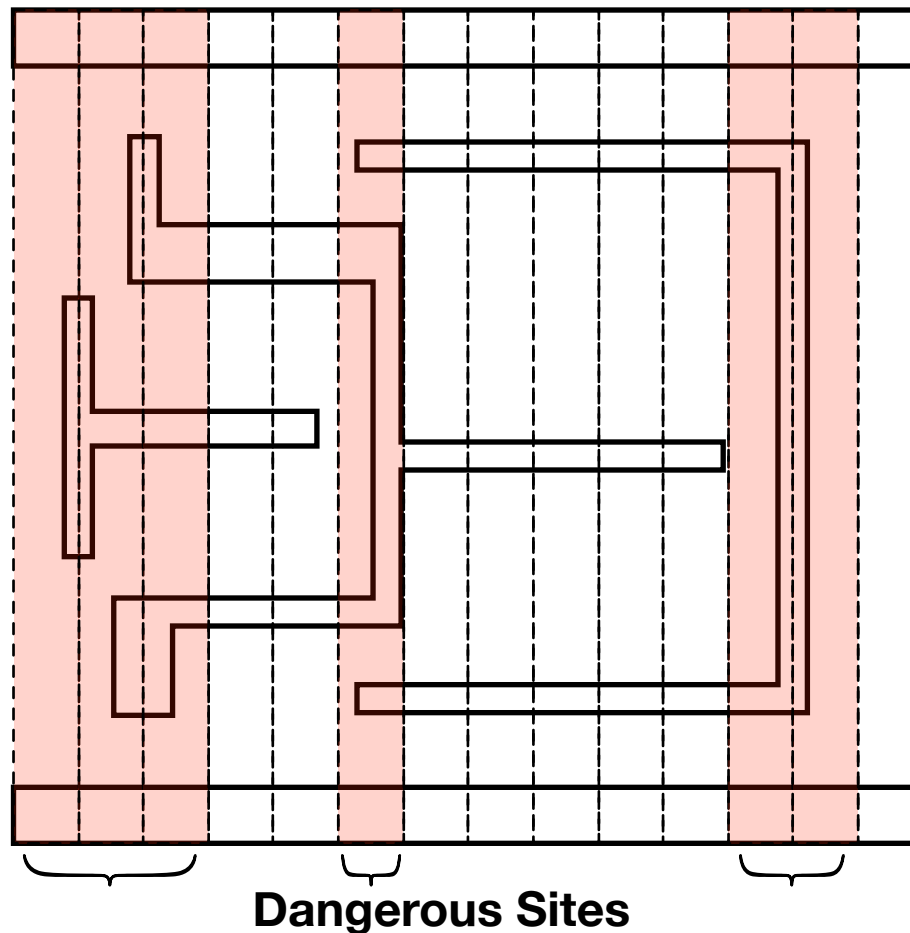


Resolve stitch errors by proper placement

# Dangerous Site Representation



- A cell is divided into sites (poly pitch)
- Sites that contain susceptible segments are marked as “dangerous sites”



# Problem Formulation



- Input
  - Initial placement
  - Dangerous site information for each standard cell (precomputed)
- Output
  - New placement with optimized wirelength and minimum stitch errors
  - MEBL friendliness

# Single Row Placement & Previous Work



- Given a set of ordered cells  $c_1, c_2, \dots, c_n$ , place cells horizontally to minimize objectives such as wirelength or movement
- Previous work on single row algorithm
  - Conventional objectives
    - [Brenner+, DATE'00], [Kahng+, GLSVLSI'04], Abacus [Spindler+, ISPD'08], [Taghavi+, ICCAD'10]
  - TPL awareness
    - [Yu+, ICCAD'13]:  $O(mnK)$
    - [Kuang+, ICCAD'14]

Note:  $\tau = 10, \phi = 1, \nu = 1$  in the experiment

# Single Row Placement



- Given a set of ordered cells  $c_1, c_2, \dots, c_n$ , with maximum cell displacement  $M$ 
  - Minimize wirelength and stitch errors
  - An algorithm supports a cost function generalizes wirelength, movement and stitch errors

$$cost_i(p_i) = \tau \cdot WL(p_i) + \phi \cdot MOV(p_i) + \nu \cdot SP(p_i)$$

Movement

Wirelength cost

Stitch error penalty

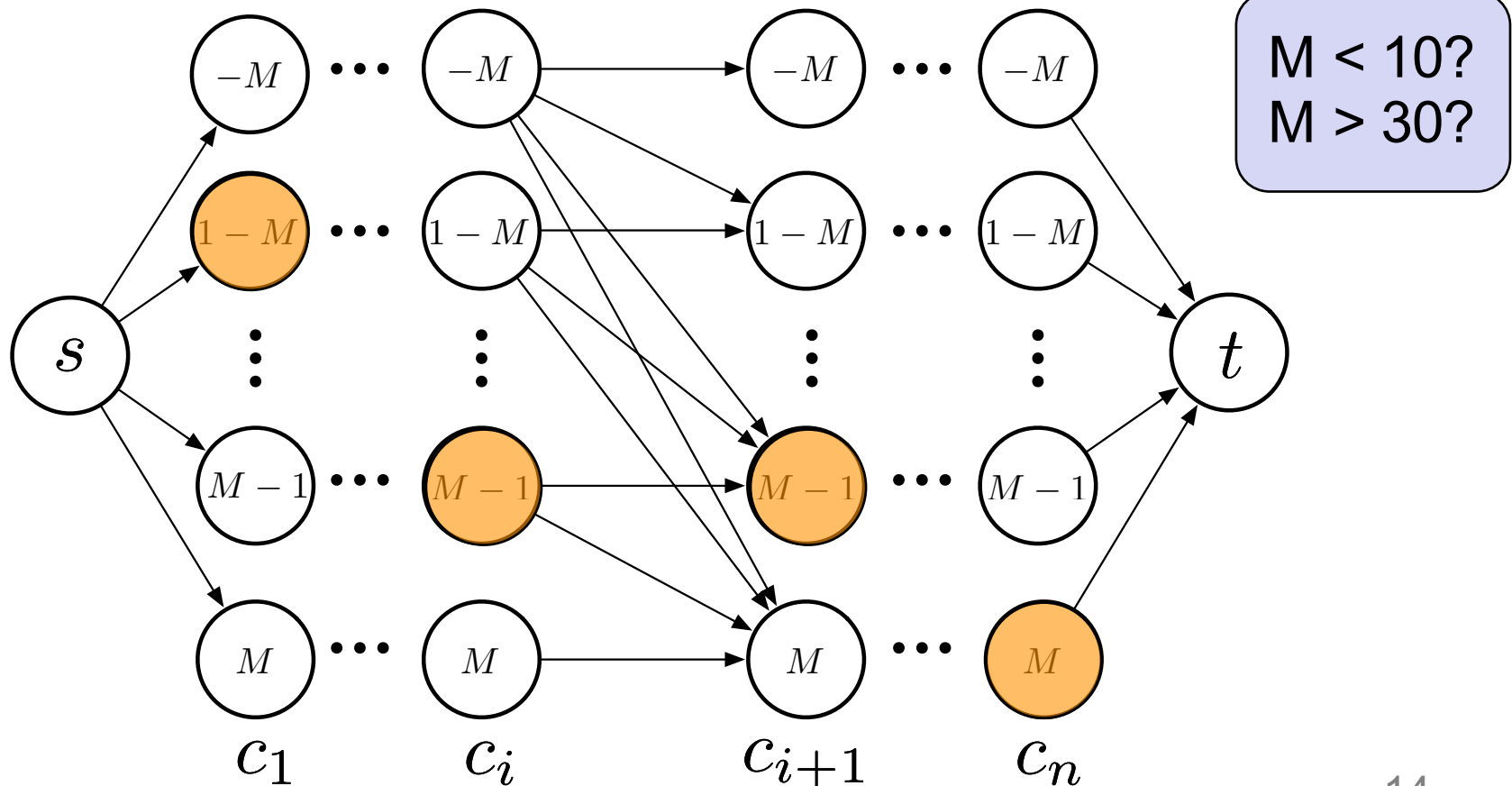
$$SP(p_i) = \begin{cases} 0, & \text{no stitch error} \\ \text{large number}, & \text{stitch error} \end{cases}$$

Note:  $\tau = 10, \phi = 1, \nu = 1$  in the experiment

# Single Row Placement



- Given a set of ordered cells  $c_1, c_2, \dots, c_n$ , with maximum cell displacement  $M$ 
  - Shortest path solved by dynamic programming
  - $O(nM^2)$

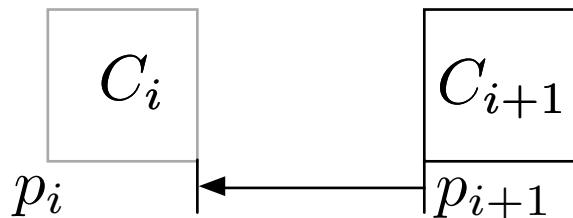


# Speedup with Pruning Techniques

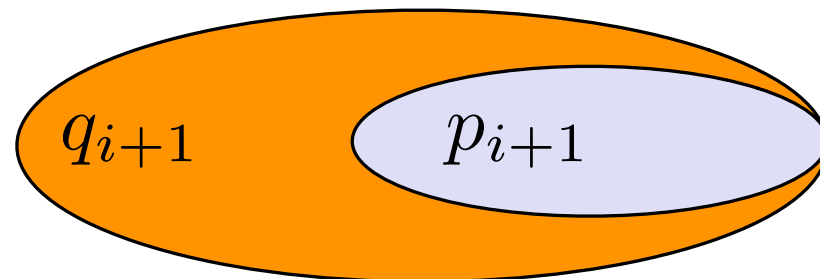
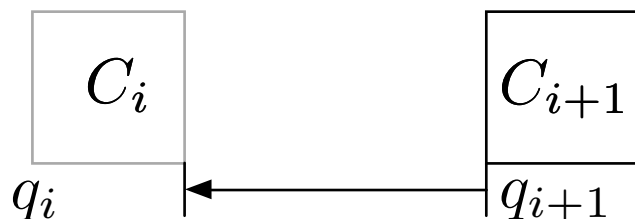


- Pruning technique 1
  - Let  $t_i(p_i)$  denote the cost of placement solution from  $c_1$  to  $c_i$  in which  $c_i$  is placed at  $p_i$
  - Comparing two solutions  $\alpha_i(p_i)$  and  $\alpha_i(q_i)$ , if  $t_i(p_i) \geq t_i(q_i)$  and  $p_i \geq q_i$ , then  $\alpha_i(p_i)$  is inferior to  $\alpha_i(q_i)$ .
  - Prune inferior solutions

Solution  $\alpha_i(p_i)$



Solution  $\alpha_i(q_i)$

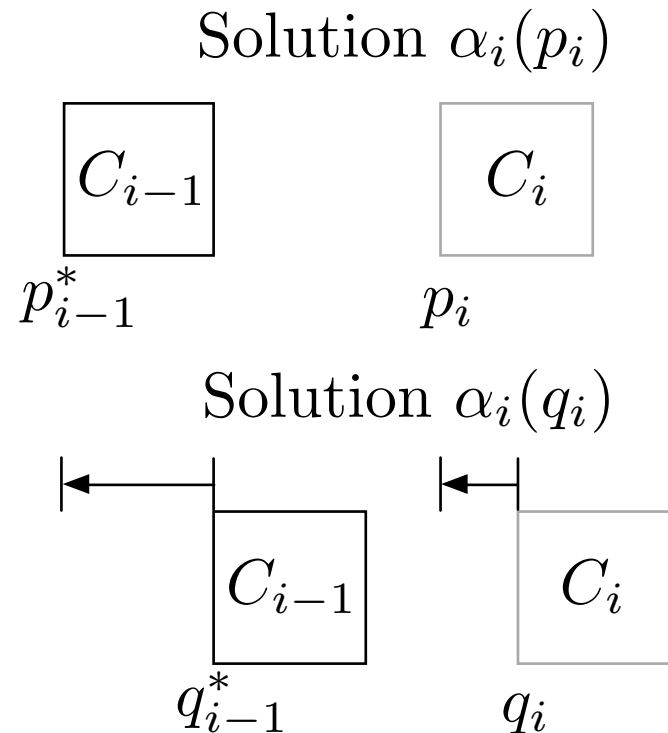
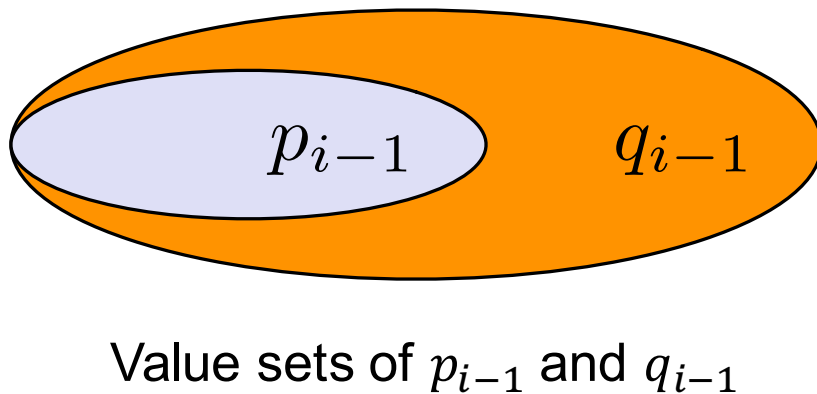


Value sets of  $p_{i+1}$  and  $q_{i+1}$

# Speedup with Pruning Techniques



- Pruning technique 2
  - Let  $p_{i-1}^*$  be the optimal position of cell  $c_{i-1}$  when cell  $c_i$  is placed at  $p_i$
  - Let  $q_{i-1}^*$  be the optimal position of cell  $c_{i-1}$  when cell  $c_i$  is placed at  $q_i$
  - If  $q_i \geq p_i$ , then  $q_{i-1}^* \geq p_{i-1}^*$
  - Reduce searching ranges

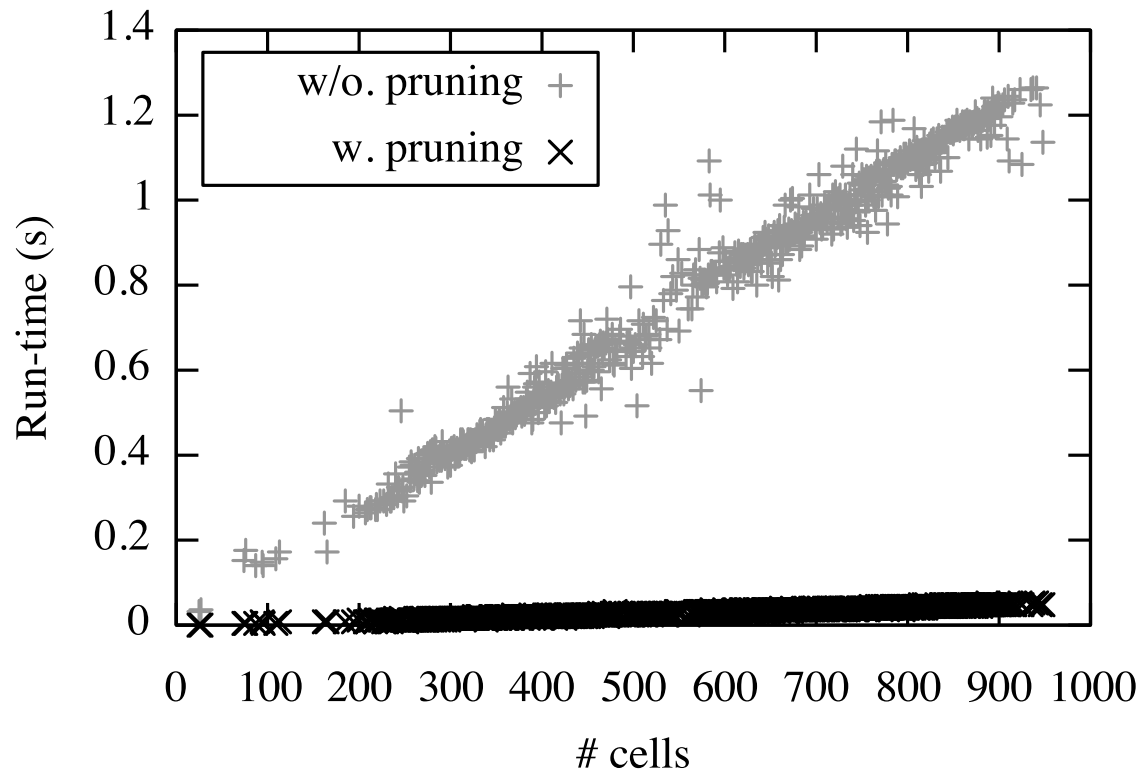




# Effectiveness of Speedup Techniques



- **$O(nM)$**  complexity
  - Requirements:  $cost_i(p_i)$  only depends on  $p_i$
  - 30x speedup
  - Keep **optimality**



# Resolve Stitch Errors in Dense Regions



- Global swap to smooth out density

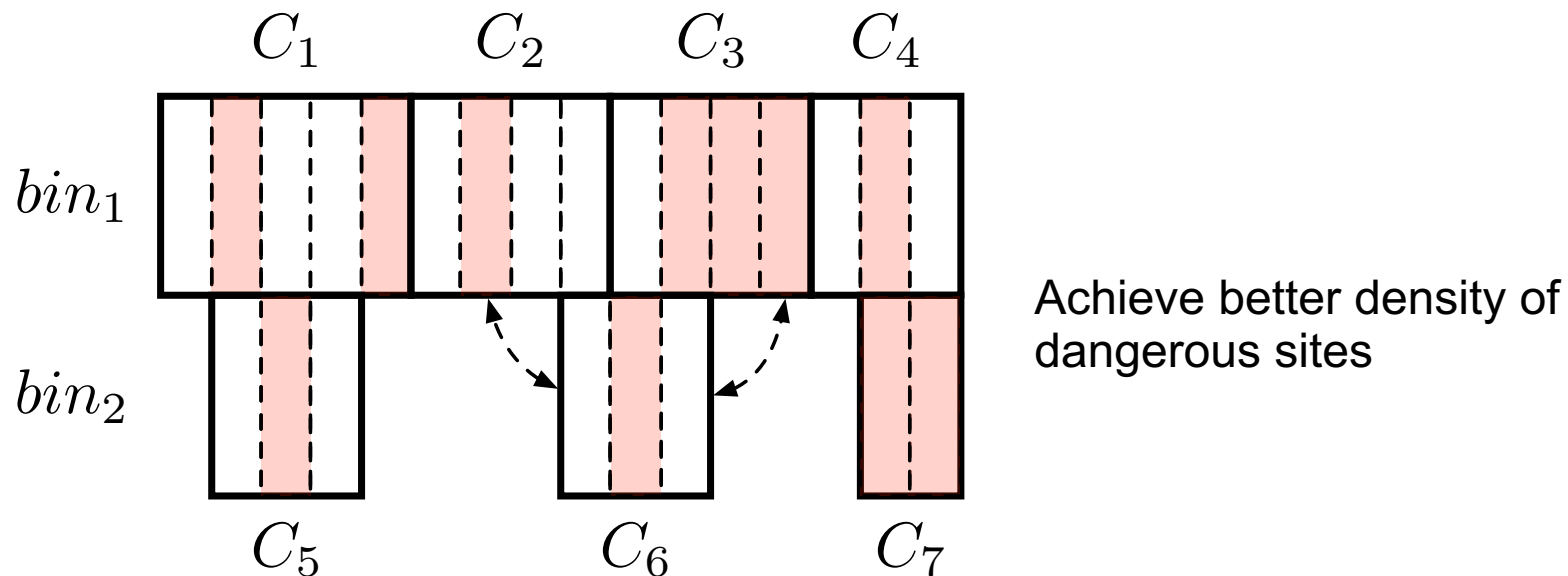
- $score(c_i, c_j) = \Delta sHPWL - \lambda \cdot P_{ds} - \mu \cdot P_{ov}$  Overlap penalty

sHPWL change

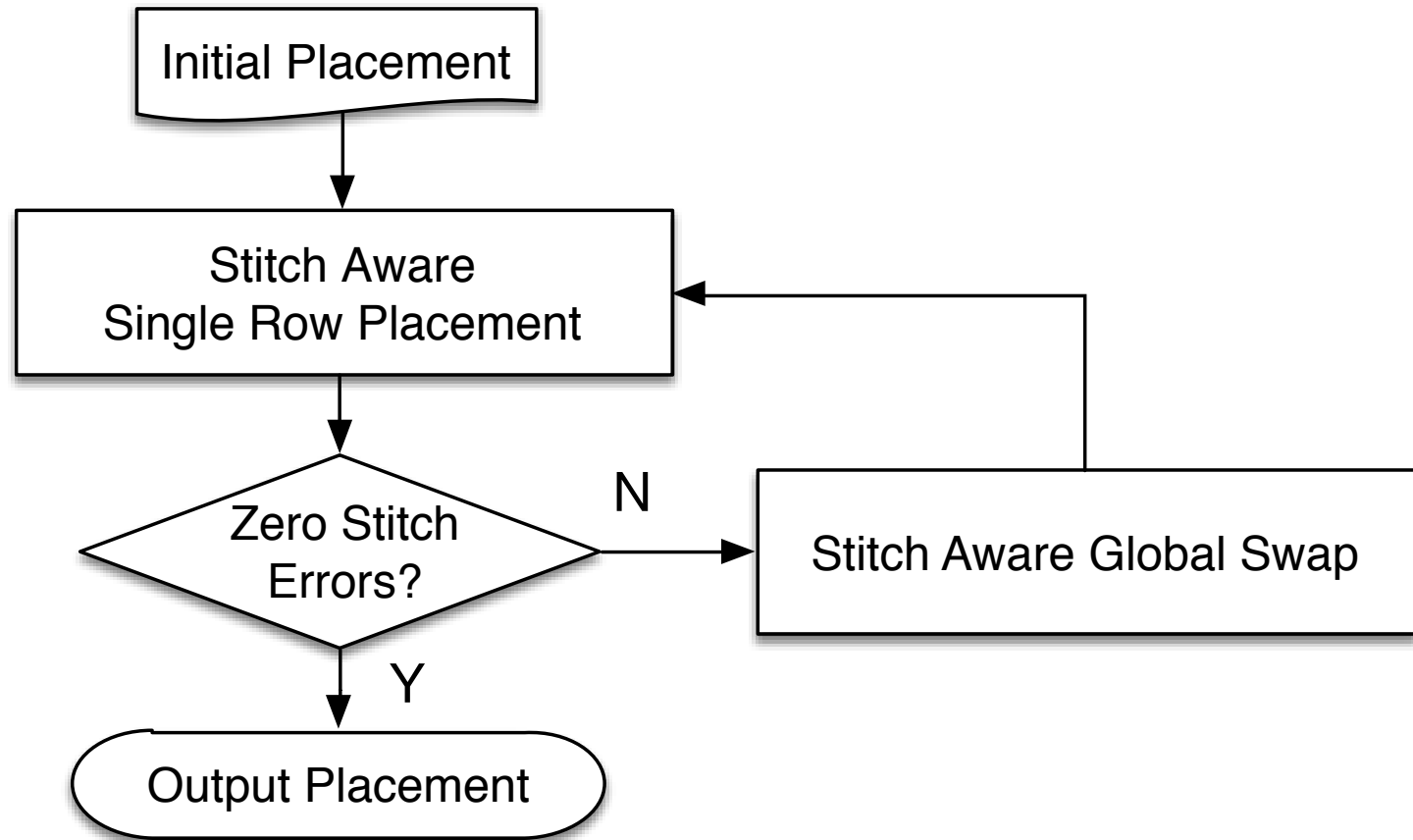
Normalized penalty of dangerous site density

$$P_{ds} = \max(0, |D'_{ds}(i) - D'_{ds}(j)| - |D_{ds}(i) - D_{ds}(j)|) \cdot A_b$$

$D_{ds}(i)$ : the density of dangerous sites in bin  $B_i$  before swap  
 $D'_{ds}(i)$ : the density of dangerous sites in bin  $B_i$  after swap  
 $A_b$ : bin area



# Overall Flow



# Experimental Environment Setup



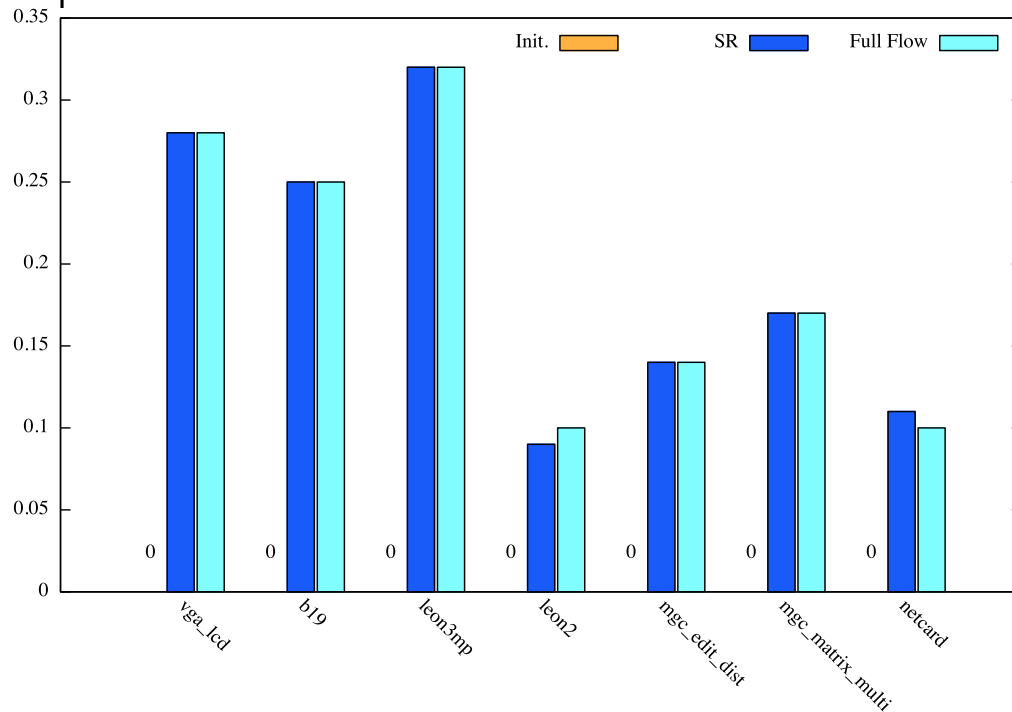
- Implemented in C++
- 8-Core 3.4GHz Linux server with 32GB RAM
- ICCAD 2014 contest benchmark
  - Mapped to Nangate 15nm Standard Cell Library
  - Legalized with RippleDP [Chow+, ISPD'14]

Design	#cells	#nets	#blockages
vga_lcd	165K	165K	0
b19	219K	219K	0
leon3mp	649K	649K	0
leon2	794K	795K	0
mgc_edit_dist	131K	133K	13
mgc_matrix_mult	155K	159K	16
netcard	959K	961K	12

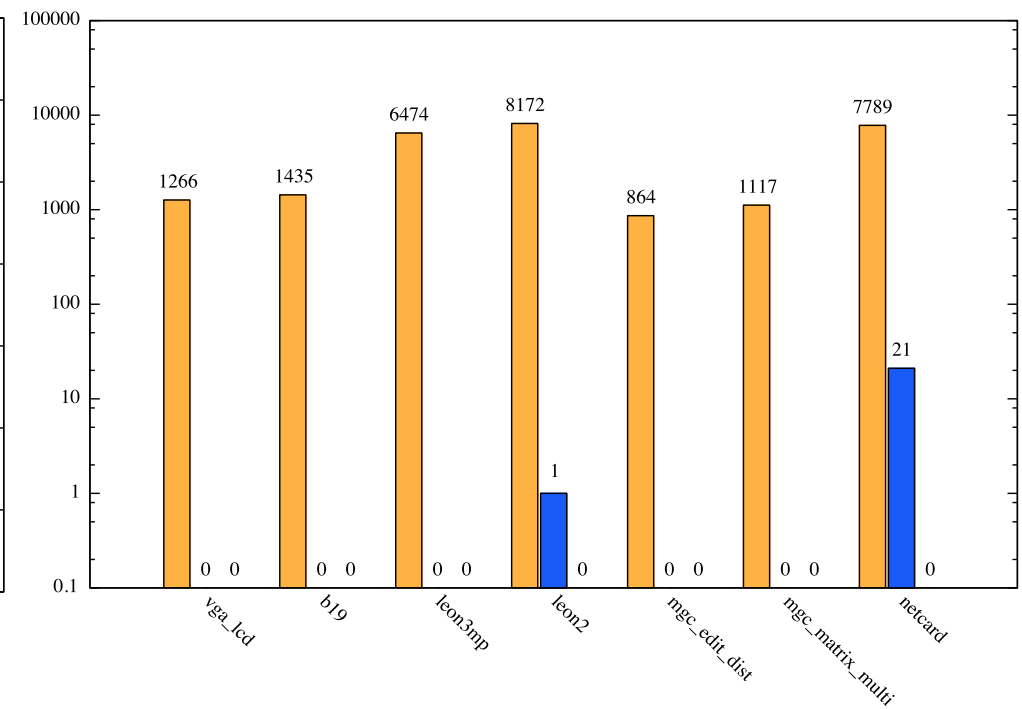
# Experimental Results



## Wirelength Improvement %



## Final Stitch Errors



Init.: initial input placement

SR: single row algorithm only

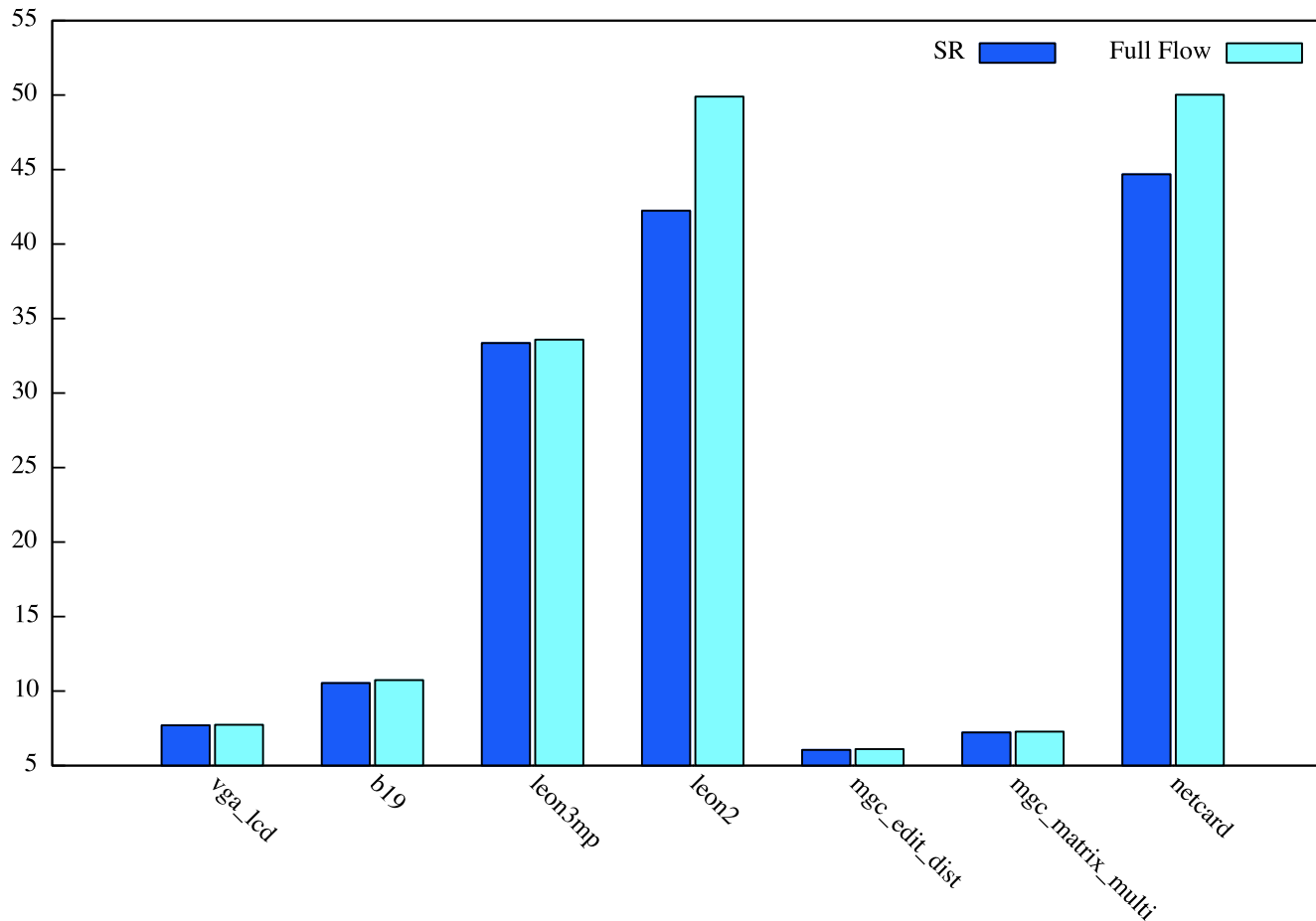
Full Flow: apply full flow including single row algorithm and global swap

# Runtime Comparison



- Full flow is slightly slower than SR
  - Only apply to regions still containing stitch errors

Runtime (s)



# Conclusion



- Methodology to handle e-beam stitch errors during detailed placement stage
- A **linear** time single row algorithm with highly-adaptable objective functions
- Can be utilized in existing CAD tool on optimizing: **Wire-length**; **Routability**; **Congestion**, etc.
- Future work
  - Consider interaction between placement and routing for EBL friendliness



Thanks